

Tuesday, April 21	
09:00 – 19:00	Automotive Skills Alliance-ASA Conference (Amphitheater)

Wednesday, April 22			
The participants are encouraged to attend any activity in any TRACK that would interest them (except the ones marked as restricted)			
Time frame	Track 1 TECHNOLOGIES of INTERCONNECTIONS in ELECTRONICS the 35 <sup>th</sup> edition Industry-Wide Student Challenges		Track 2 TRIEME & SEMICONDUCTORS/ECSA
09:00 – 14:30	Registration & Exhibition opening - Welcome coffee (1 <sup>st</sup> floor hall)		09.00 – 17.00 TRIEME - Room 50 places (Floor 1, Room 101) SEMICONDUCTORS/ECSA – Room 35 places (Floor 3, room 1)
09:00 – 13:00	Pannel Discussion: Needed Skills, Quality Jobs and Preparedness (Contributors: Representatives from the Industry, Academia, Government Institutions, NGOs)  (Amphitheater)		
11:00 – 11:15	Coffee Break (1 <sup>st</sup> floor hall)		
11:15 – 13:00	Workshop (Amphitheater)		
13:00 – 14:00	Light Lunch (1 <sup>st</sup> floor hall)		
14:00 – 18:00	TIE <sub>EPLUS</sub> Final Stage (public event) (Amphitheater)		
14:00 – 18:00	Technical meetings TIE <sub>μ</sub> , TIE <sub>M PLUS</sub> si TIE <sub>T PLUS</sub> (Floor 3, room 2)		
18:00 – 18:30	Coffee Break (1 <sup>st</sup> floor hall)	Steering Committee Meeting (RESTRICTED to Committee members)	

		(Floor 3, room 1)	
18:30 – 19:15	TIE <sub>EPLUS</sub> Demystifying the resolution of the proposed topics (Amphitheater)		
19:15	Welcome cocktail and expo networking (1 <sup>st</sup> floor hall)		

Thursday, April 23		
The participants are encouraged to attend any activity in any TRACK that would interest them (except the ones marked as restricted)		
Time frame	Track 1 TECHNOLOGIES of INTERCONNECTIONS in ELECTRONICS the 35 <sup>th</sup> edition Industry-Wide Student Challenges	Track 2 TRIEME & SEMICONDUCTORS/ECSA
08:00 – 14:00	Registration - Welcome coffee (1 <sup>st</sup> floor hall)	
08:30 – 10:15	TIE <sub>EMPLUS</sub> Final Stage (public event) (Floor 1, Cafeteria)	TIE <sub>TPLUS</sub> Final Stage (public event) (Floor 3, Room 2)
10:15 – 10:30	Coffee Break (1 <sup>st</sup> floor hall)	
10:30 – 12:15	TIE <sub>EMPLUS</sub> Final Stage (public event) (Floor 1, Cafeteria)	TIE <sub>TPLUS</sub> Final Stage (public event) (Floor 3, Room 2)
12:15 – 13:15	Lunch (1 <sup>st</sup> floor hall)	
13:15 – 15:00	TIE <sub>μ</sub> Final Stage (public event) (Floor 3, room 1)	
15:00 – 15:15	Coffee Break (1 <sup>st</sup> floor hall)	

15:15 – 16:00	TIEμ Final Stage (public event) <i>(Floor 3, room 1)</i>			
15:15 – 17:00	Committee Assessment meetings (RESTRICTED to Committee members) <i>(ETTI Faculty Rooms)</i>			
	TIE <sub>MPLUS</sub>	TIE <sub>TPLUS</sub>	TIEμ	
15:15 – 17:00	Technical Meetings TIE <sub>E</sub> <i>(Floor 3, room 1+2)</i> TIE <sub>M</sub> <i>(Floor 1, room 101)</i>			
17:15 – 18:45	Common Session: TIEμ, TIE <sub>M PLUS</sub> si TIE <sub>T PLUS</sub> Demystifying the resolution of the proposed topics <i>(Amphitheater)</i>			
18:45 – 20:30	Award Ceremony Keynote1: <i>(Amphitheater)</i>			
20:30	Gala dinner <i>(.....)</i>			

Friday, April 24 <i>The participants are encouraged to attend any activity in any TRACK that would interest them            (except the ones marked as restricted)</i>		
Time frame	Track 1 TECHNOLOGIES of INTERCONNECTIONS in ELECTRONICS the 35 <sup>th</sup> edition Industry-Wide Student Challenges	
08:00 – 08:30	Preliminary activities	
	TIE <sub>E</sub> <i>(Floor 3, room 1+2)</i>	TIE <sub>M</sub> <i>(Floor 1, room 1+2)</i>
08:30 – 12:30	TIE <sub>E</sub> Hackathon <i>(Floor 3, room 1+2)</i>	TIE <sub>M</sub> Hackathon <i>(Floor 1, room 1+2)</i>
12:30 – 13:30	Lunch <i>(1<sup>st</sup> floor hall)</i>	
13:30 – 16:30	TIE <sub>E</sub> Assessments (public events) <i>(Floor 3, room 1+2)</i>	TIE <sub>M</sub> Assessments (public events) <i>(Floor 1, room 1+2)</i>
18:30 – 19:00	TIE Steering Committee Meeting (RESTRICTED to Committee members) <i>(???? Room)</i>	
19:00	Awarding TIE <sub>E</sub> , TIE <sub>M</sub> & Conclusion speeches <i>(Amphitheater)</i> Closure Banquet <i>(.....)</i>	

Saturday, April 25	
09:30 – 10:30	Looking Forward. Farwell discussion for the next TIE Industry-wide student challenge, TIE 2027 <i>(1<sup>st</sup> floor hall)</i>